

The screenshot displays a patent database search interface. The top menu bar includes File, View, Edit, Tools, Window, and Help. Below the menu is a toolbar with various icons. The main window is divided into several sections:

- Drafts:** A list of draft entries, each starting with "BRS:" followed by a date and time stamp.
- Pending:** A section for pending entries.
- Active:** A large section containing a detailed list of patent records. Each record includes a date/time stamp, a title, and a brief description. Examples include:
 - L2: (86) 2003/0104654 2002/0027273 36 468 Des. 384,844 Des. 402,638
 - L3: (86) 2003/0104654 2002/0027273 36 468 394,844 402,638
 - L4: (21) 2003/0104654 2002/0027273 394,844 402,638
 - L1: (50) 5,252,857
 - L5: (504) cavity near4 defin\$4 near6 (lead leadframe)
 - L6: (2370863) (encapsula\$3 encapsulation mold\$3 resin)
 - L7: (132)\$ with 6
- Failed:** A section for failed entries.
- Saved:** A section for saved entries, including details like "(2251450) (encapsula\$3 encapsulation mold\$3 resin)".

On the right side of the interface, there are search filters and options:

- DB:** USPAT-US POPUB EPO JPO DERWENT IBM TDB
- Default operator:** OR
- Options:** Plurals, Highlight all hit terms initially
- Results:** 5 with 6

A handwritten note "Sept 2003" is visible in the center-right area of the screen.

At the bottom, there is a table with columns: Inventor, Document ID, Issue D/P, Title, Current D, Current X/R, Retrieval C, S, C, P, Z, I, Image Doc, B, P. The table lists several patent entries with their respective details.

	Inventor	Document ID	Issue D/P	Title	Current D	Current X/R	Retrieval C	S	C	P	Z	I	Image Doc	B	P
1	Huang, Chien Pi	US 200200272	200203-12	Semiconductor package and fabricating method there	257/678	257/E23,046							US 20020027		
2		JP 05175399 A	199307-3	Resin-sealed semiconductor device prodn. - comprises									JP 05175399		
3		JP 60111432 A	198506-4	Resin sealing die for semiconductor device - comprises									JP 60111432		
4		JP 60109236 A	198506-4	Resin moulding appts. for sealing semiconductor devic									JP 60109236		
5		JP 53078949 A	197807-3	Metal mould for thermoplastic resin - used for holding									JP 53078949		
6	ARAI, T et al	US 4751611 A	198806-4	Package structure for semiconductor element e.g. IC									US 4751611		
7	Adachi, Masaki	US 6091139 A	200007-13	Semiconductor device	257/680	257/666							US 6091139		
8	Alfaro, Rafael C	US 5458716 A	199510-8	Methods for manufacturing a thermally enhanced mold	156/245	156/292							US 5458716		